nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

| Supplier | | User Part Number | | | | |
|--|---------------------------------------|---|-------------|-----------|------------|-----------|
| Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test | | BZT52-B7V5-Q Part Description | | | | |
| | | | | | | |
| | | SMD package | | | | |
| | | Test Conditions | Duration | # Lots | # Quantity | # Rejects |
| | | | TEST | | | |
| | Pre- and Post-Stress | | | | | |
| # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below |
| | | JESD22-A113 | | | | |
| | | Bake Tamb = 125 °C | 24 hours | | | |
| | PC | Soak Tamb = 85 °C, RH = 85% | 168 hours | | | |
| # A1 | Preconditioning | Reflow soldering | 3 cycles | 1514 | 64430 | 0 |
| | | MIL-STD-750-1 | | | | |
| | HTRB | M1038 Method A | | | | |
| | 5 1 | Tj = Tjmax, VR = 80 % of rated reverse | | | | |
| # B1 | Bias | voltage | 1000 hours | 250 | 11400 | 0 |
| | | MIL-STD-750-1 | | | | |
| | 660 B | M1038 Method B | | | | |
| # D11 | SSOP Steady State Operational | Tj = Tjmax, Iz = 100% of max. datasheet reverse current | 1000 have | | 1020 | 0 |
| # B1b | Steady State Operational | Teverse current | 1000 hours | 44 | 1920 | 0 |
| | тс | JESD22-A104 | | | | |
| # A4 | Temperature Cycling | -65 °C to Timax, not to exceed 150°C | 1000 cycles | 311 | 14080 | 0 |
| # 44 | Temperature cycling | | 1000 Cycles | 511 | 14000 | 0 |
| | UHAST | JESD22-A118 | | | | |
| # A3 or | Unbiased HAST | Tamb = 130 °C, RH = 85 % | 96 hours | 311 | 14080 | |
| " /\3 0 1 | | JESD22-A102 | | | | 0 |
| | AC | Tamb = $121 ^{\circ}C$, RH = $100 ^{\circ}M$ | | | | |
| # A3 alt | Autoclave | Pressure = $205 \text{ kPa} (29.7 \text{ psia})$ | | | | |
| " No uit | | | | | | |
| | H3TRB | JESD22-A101 | | | | |
| | High Humidity High | Tamb = 85 °C, RH = 85%, VR = 80 % of | | | | |
| # A2 alt | Temperature Reverse Bias | | 1000 hours | 311 | 14080 | 0 |
| | · · · · · · · · · · · · · · · · · · · | MIL-STD-750 Method 1037 | | | | |
| | IOL | ton = toff, devices powered to insure ΔT_j = | | | | |
| # A5 | Intermittent Operating Life | , , , | 1000 hours | 312 | 14120 | 0 |
| | | | | | | |
| | RSH | JESD22-A111 | | | | |
| # C8 | Resistance to Solder Heat | 260 °C ± 5 °C | 10 s | 269 | 8070 | 0 |
| | SD | | | | | |
| # C10 | Solderability | J-STD-002 | | 19 | 6660 | 0 |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| 2,68E+09 |
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